

Supporting Information

Enhanced Thermoelectric Performance of Copper Iodide Particles/Nanowires Composite in the Low-Temperature Range

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Figures

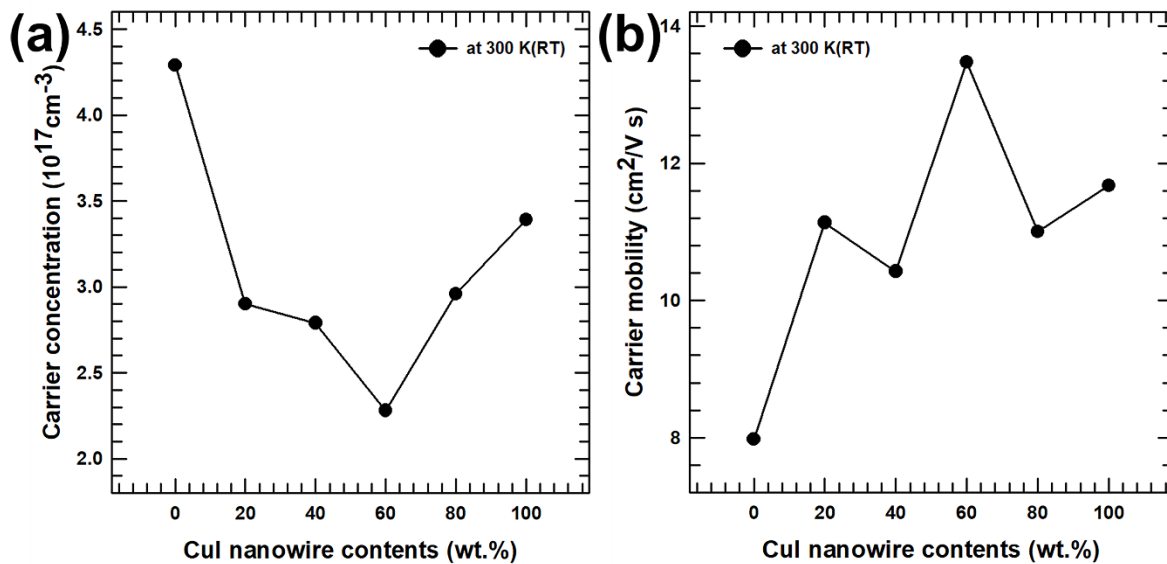


Fig. S1. CuI nanowire content dependence of (a) carrier concentration and (b) carrier mobility for CuI composites at 300 K.

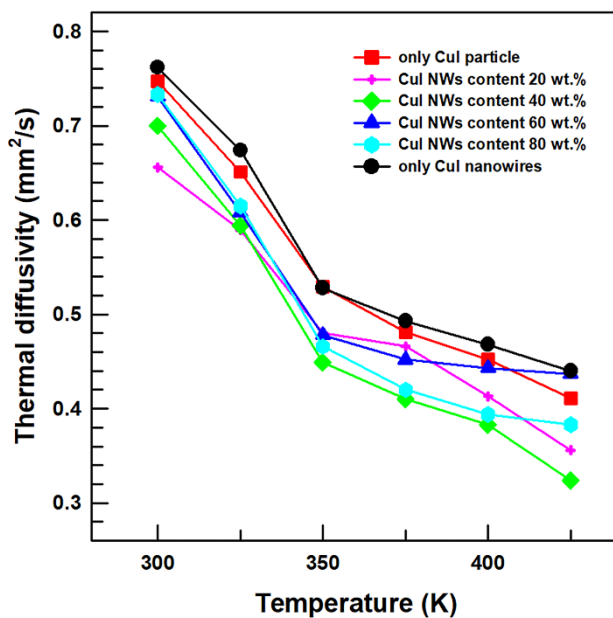


Fig. S2. Temperature-dependent thermal diffusivity of each CuI composite.